

LINQSOL™ EMC-G375



Black epoxy molding compound

- High thermal conductivity (up to 3.3 W/mK)
- Designed for fullpack TO power packages and bridge rectifier packages
- Excellent mechanical integrity

LINQSOL™ EMC-G375 is a halogen-free epoxy molding compound engineered for full-encapsulated TO3P, TO-220, TO-126, bridge rectifier packages and high power packages. It exhibits excellent molding processability and a high thermal conductivity of ~3.3 W/m·K that satisfies heat dissipation required by high performance power packages.

LINQSOL™ EMC-G375 guarantees strong performance and outstanding long-term reliability in demanding environments. This product is deliberately formulated without the inclusion of substances prohibited by the European Union RoHS and REACH. Overall, **EMC-G375** seamlessly integrates advanced material properties, safety compliance, and superior performance to deliver a reliable solution for semiconductor device encapsulation.

Specifications

Property	Value	Unit
General Properties		
Resin type	MAR+MF+OCN	-
Filler sieving size	55	µm
Filler content	85 ±2	%
Specific gravity	2.7 ±0.02	-
Spiral flow at 175 °C	85 ±25	cm
Mold shrinkage	0.003	%
Chemical Properties		
Ion content		
Chloride (Cl ⁻) concentration	5 ±1	ppm
Sodium (Na ⁺) concentration	5 ±1	ppm
Water absorption (PCT 20 h)	0.2 ±0.05%	%
pH of extract	5 ±1	-
Electrical conductivity of extract	≤ 15	µS/cm
Mechanical Properties		
Flexural strength at 25 °C	120 ±5%	MPa
Flexural modulus at 25 °C	25.5 ±5%	GPa
Electrical Properties		
Volume resistivity at 25 °C	3.0 × 10 ¹⁵	Ω · cm
Dielectric constant	4.6	MHz

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Thermal Properties		
Glass transition temperature	175 $\pm$ 5	°C
Coefficient of thermal expansion, α_1	13 $\pm$ 2	ppm/°C
Coefficient of thermal expansion, α_2	40 $\pm$ 5	ppm/°C
Gel time at 175 °C	33 $\pm$ 7	s
Thermal conductivity	$\leq$ 3.3	
Flammability rating	V-0	UL-94

Recommended mold parameters

Parameter	Value	Unit
Preheating temperature	75–95	°C
Mold temperature	170–190	°C
Transfer pressure	40–100	kg _f /cm ²
Transfer time	10–35	s
Cure time at 170–190 °C	120–270	s
Post mold cure time at 170–180 °C	4-6	h

The curing conditions provided are recommended guidelines based on typical laboratory results. Actual curing parameters should be defined and validated by the user to ensure compatibility with specific materials, part geometries, and end-use requirements. It is the user's responsibility to optimize and confirm curing conditions that meet their performance and quality standards.

Processing Instructions

- Before use, let **LINQSOL™ EMC-G375** reach room temperature (23 $\pm$ 5 °C) for 24 hours. Keep the bag unopened and stored in a dry location with a relative humidity of $\leq$ 50% during thawing to prevent moisture contamination.
- Use the materials within 48 hours after removing the product from cold storage.
- When storing unused materials, vacuum seal the product in 2 layers of PE bags packaged in moisture barrier bag and store them in a < 10 °C environment. When using the materials again, use it within 48 hours after removing the product from cold storage.

Storage and Handling

LINQSOL EMC-G375 is available in pressed pellets in a wide range of sizes to meet specific customer needs. To ensure product integrity, keep it away from oxidizing materials. For long-term storage, maintain a cold environment. The shelf life when stored below 10 °C is 183 days.

The technical information presented in this document is provided for reference only and does not constitute a guarantee of specific properties or performance. Actual results may vary depending on individual conditions and application methods. Users are strongly advised to perform their own testing and validation to determine suitability for their intended use and compliance with relevant regulations.

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